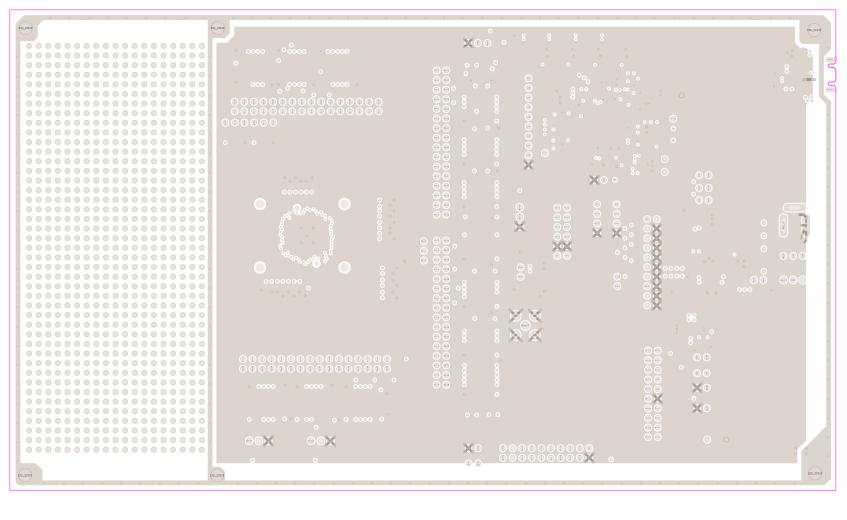
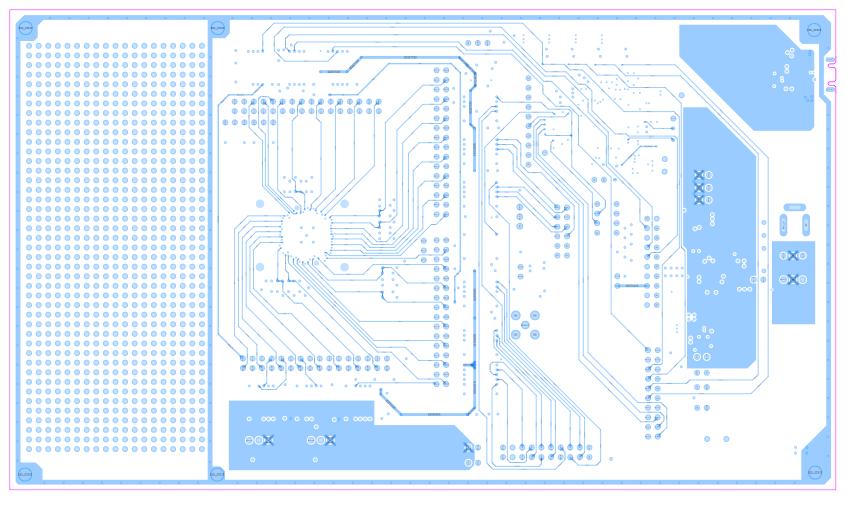


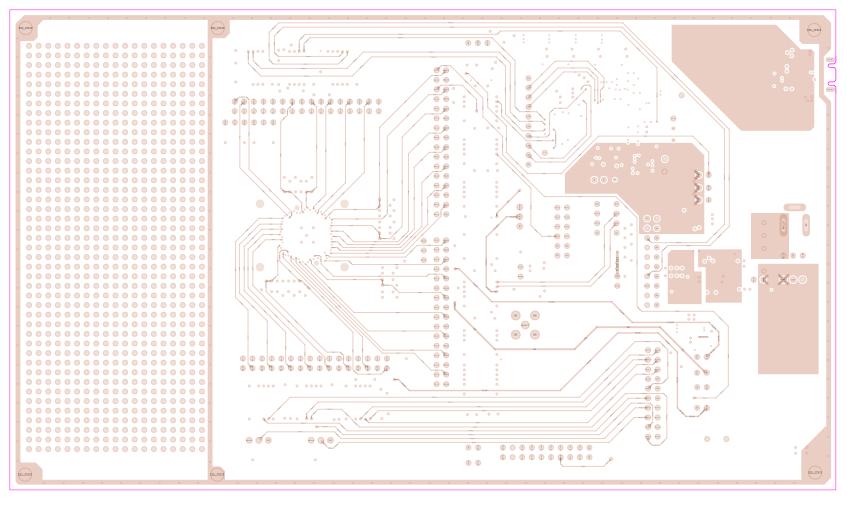
COMPONENT SIDE

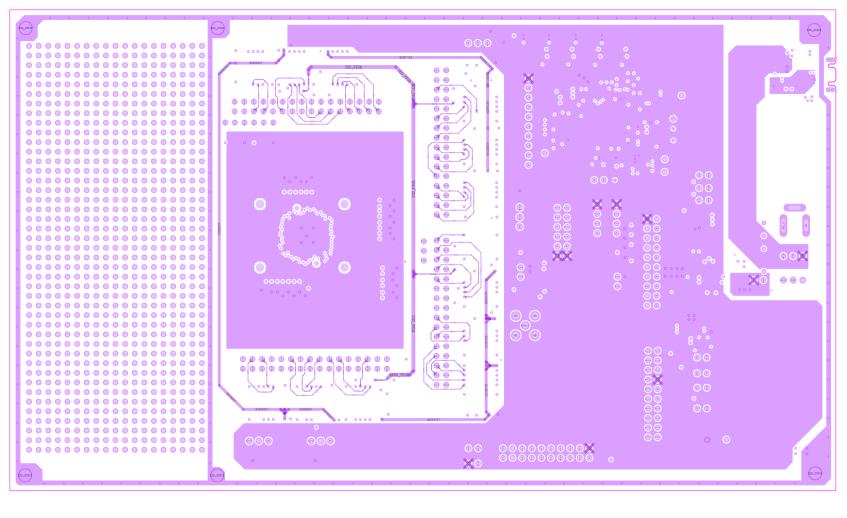


GND PLANE

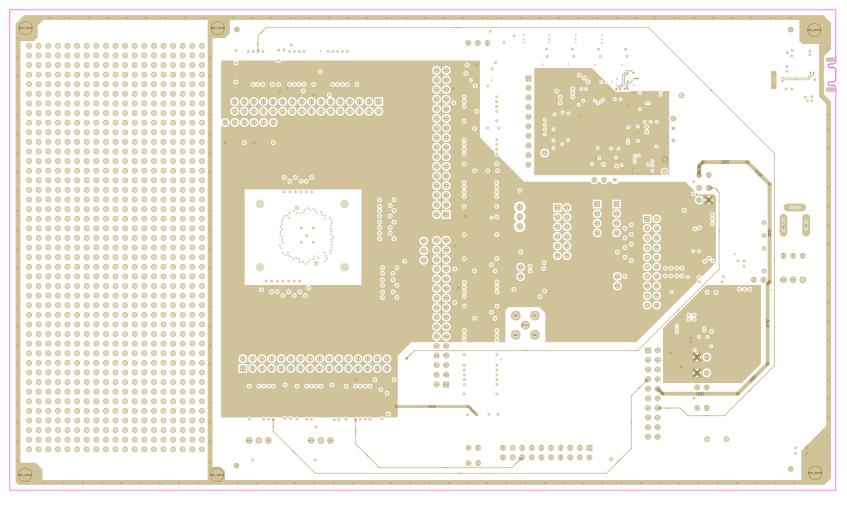


INTER1 LAYER

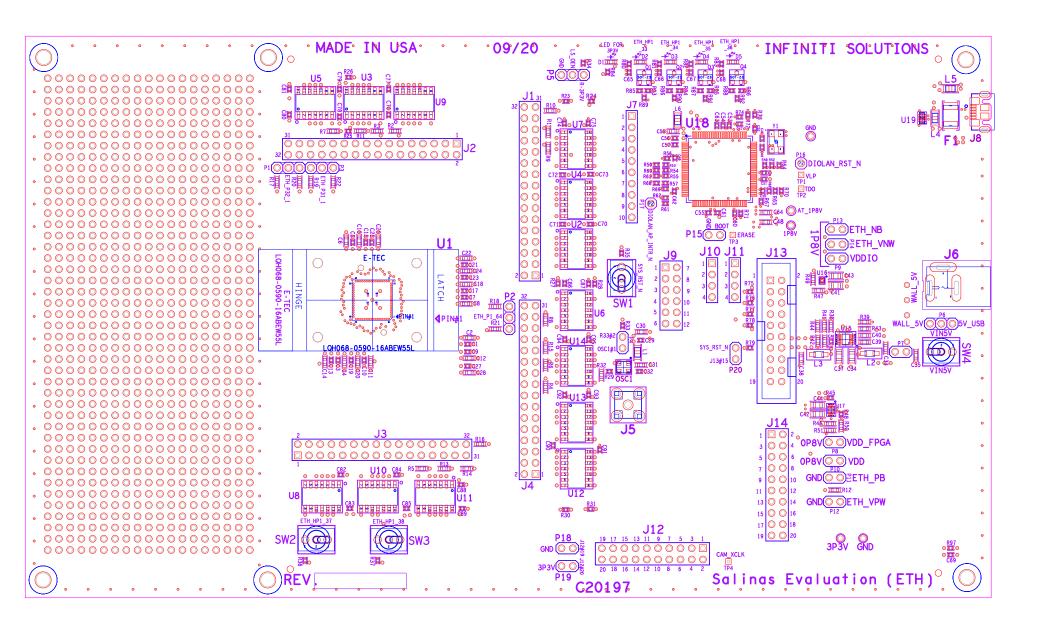




POWER PLANE

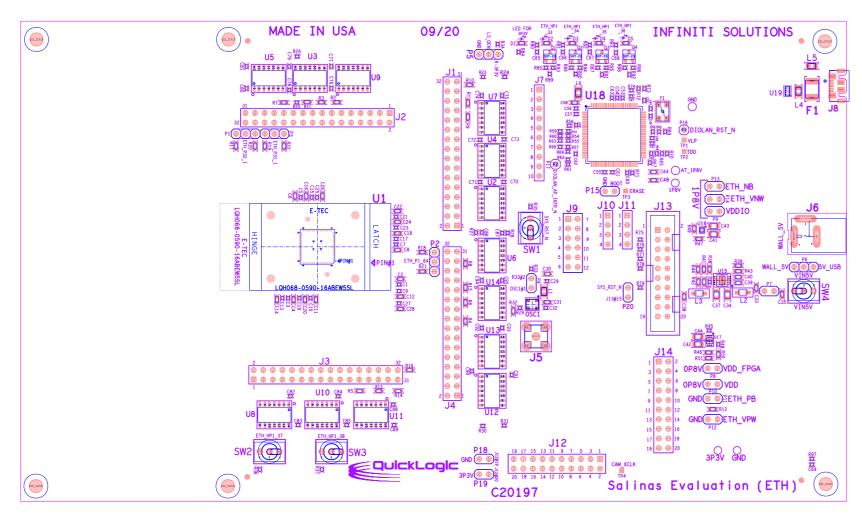


BOTTOM SIDE



1.1	09/12/20	CHANGE USB J8 AND SOME CONNECTION UPDATED IN LAYOUT	PMS	HMP	
REV. NO.	DATE	DESCRIPTION	REVISED E	PASSED	ВҮ

- * PLEASE TAPPED OFF TEST PADS TP1-TP4 AND P5 WHILE WAVE SOLDERING.
- * SOCKET U1&IT'S IC WILL BE SUPPLIED & INSTALLED BY QUICKLOGIC



ASSEMBLY TOP

50 OHM SINGLE ENDED IMPEDANCE CONTROL BOARD 100 OHM DOUBLE ENDED IMPEDANCE CONTROL BOARD SILKSCREEN TOP REQUIRED (WHITE EPOXY) 0.50z — LAYER 1 (COMP. SIDE)—50-OHM SINGLE ENDED,11 MIL TRACE 0.008° PREPREG 0.008" -LAYER 2 (GND PLANE) `CORE 0.014" 0.5/0.5 ——LAYER 3 (INTER-1) 0.063* +/- 10% PREPREG 0.008" ——LAYER 4 (INTER-2) CORE 0.014" 0.5/0.5 -LAYER 5 (PWR PLANE) PREPREG 0.008" -LAYER 6 (SOLDER SIDE)-90-OHM DIFF IMPEDANCE ,9 MIL TRACE,10 MIL SEPARATION. 0.50z

DFM ANALYSIS						
MINIMUM	LINE/LINE	0.0058"				
AIRGAP	LINE/DRILL	0.010"				
	DRILL/DRILL	0.010"				
MIN. T	0.007"					
MIN	0.010"					
FIL	NO					
IMF	YES					

FINGER PLATING: N/A	UNLESS OTHERWIS DIMENSIONS ARE TOLERANCES ARE .XXX = .005 DSNR:		INFINITI SOLUTIONS 3910 N, FIRST STREET, San Jose, CA 95134 Phone (408) 923-7300 FAX (408) 251-5431		
MATERIAL:	SMM CHECKED:	09/12/20 DATE:	CUSTOMER NAME: QUICKLOGIC		
HI TEMP. FR4	POSITIONS:	1	DEVICE: Salinas Evaluation (ETH)		
(170C Tg)	FOR BIB X⊲→C DESIGN	> Y \(\frac{\dagger}{\tau} \)	IS DESIGN NO: C20197 Design Rev: 1.1		
SOLDER MASK: LAYERS:	MATRIX				
GREEN LPI 06	STEP		SCALE 1/1 SHEET 1 OF 1 SIZE: D		